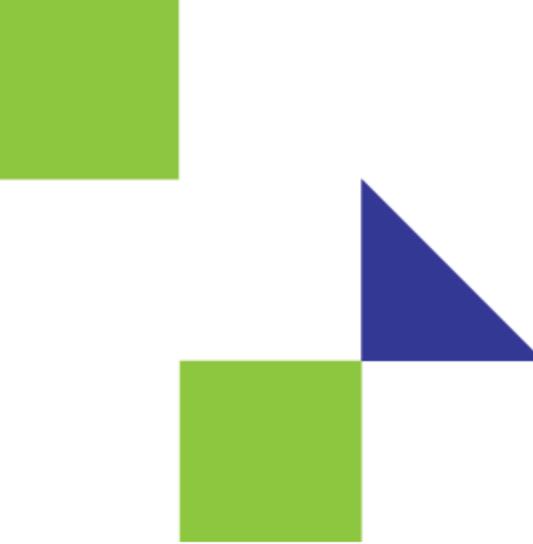




OCP SUMMIT

March 20-21
2018
San Jose, CA

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Immersion Cooling for Green Computing

Fangzhi/Director/Alibaba

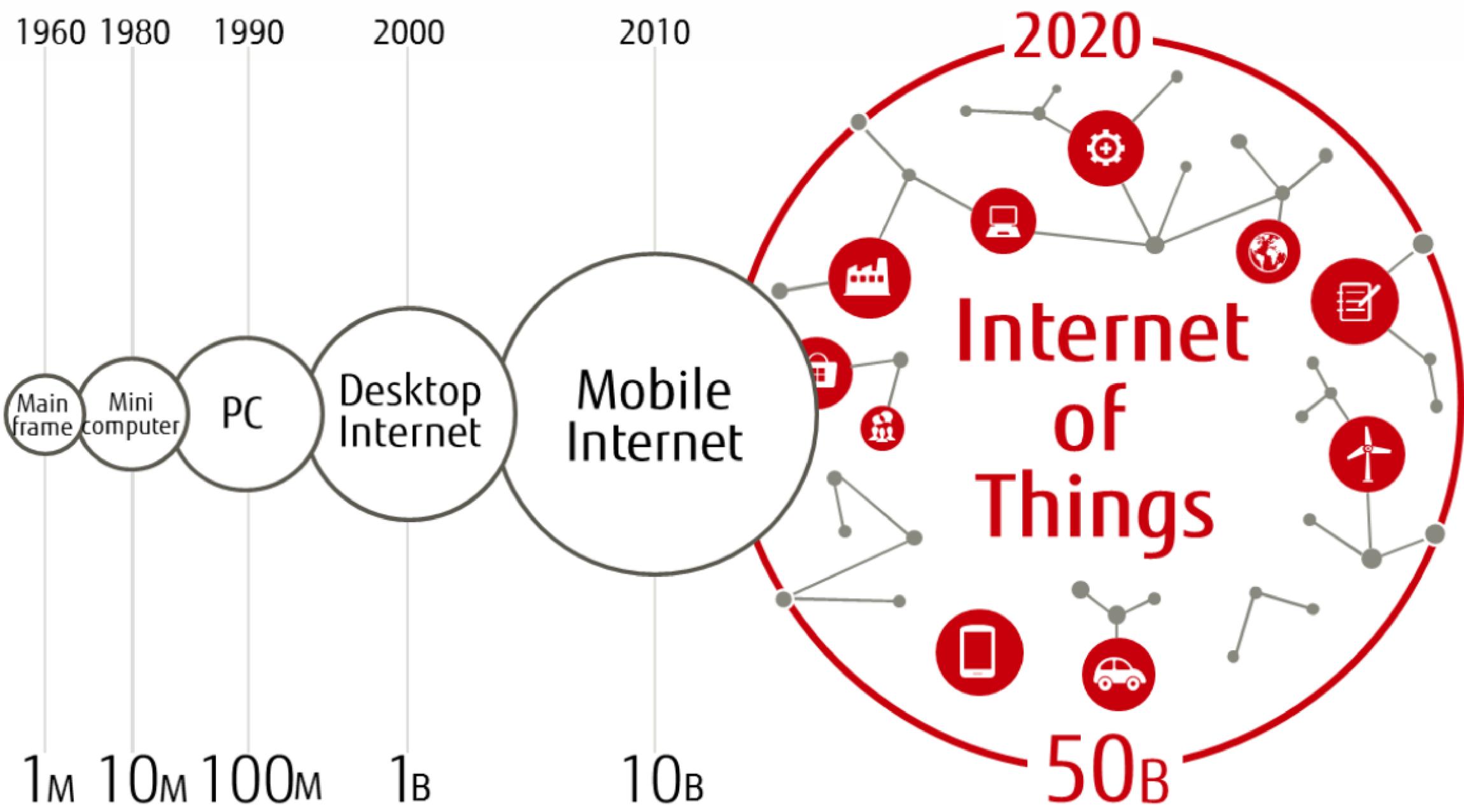
OPEN. FOR BUSINESS.



Key Points

- 1、 Background**
- 2、 Today' s Datacenter Challenges
- 3、 Why immersion cooling?
- 4、 Challenges of immersion cooling
- 5、 Alibaba progress and plan

Background : Big Data Era

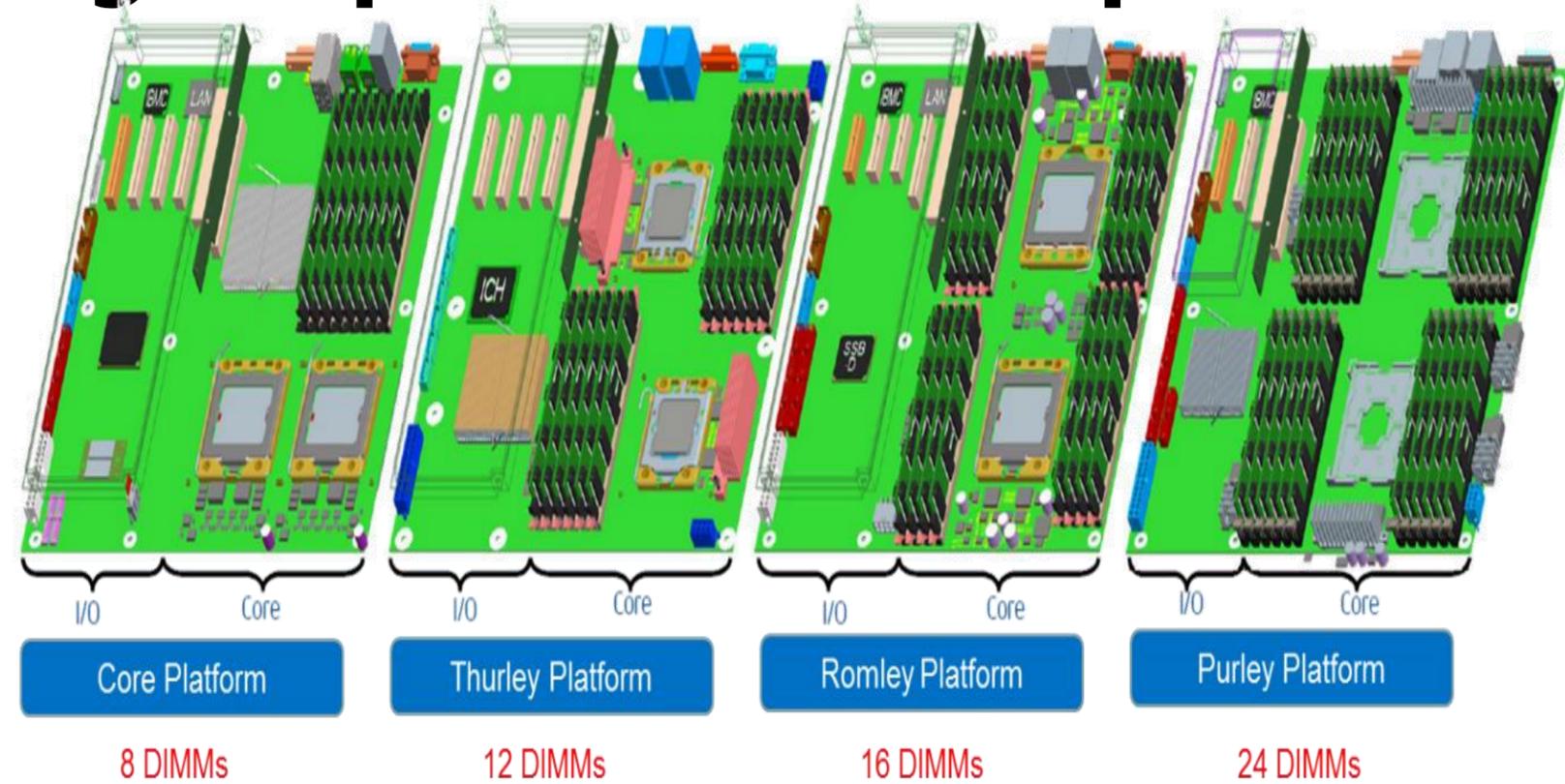


+44ZB
Data generated per year by 2020

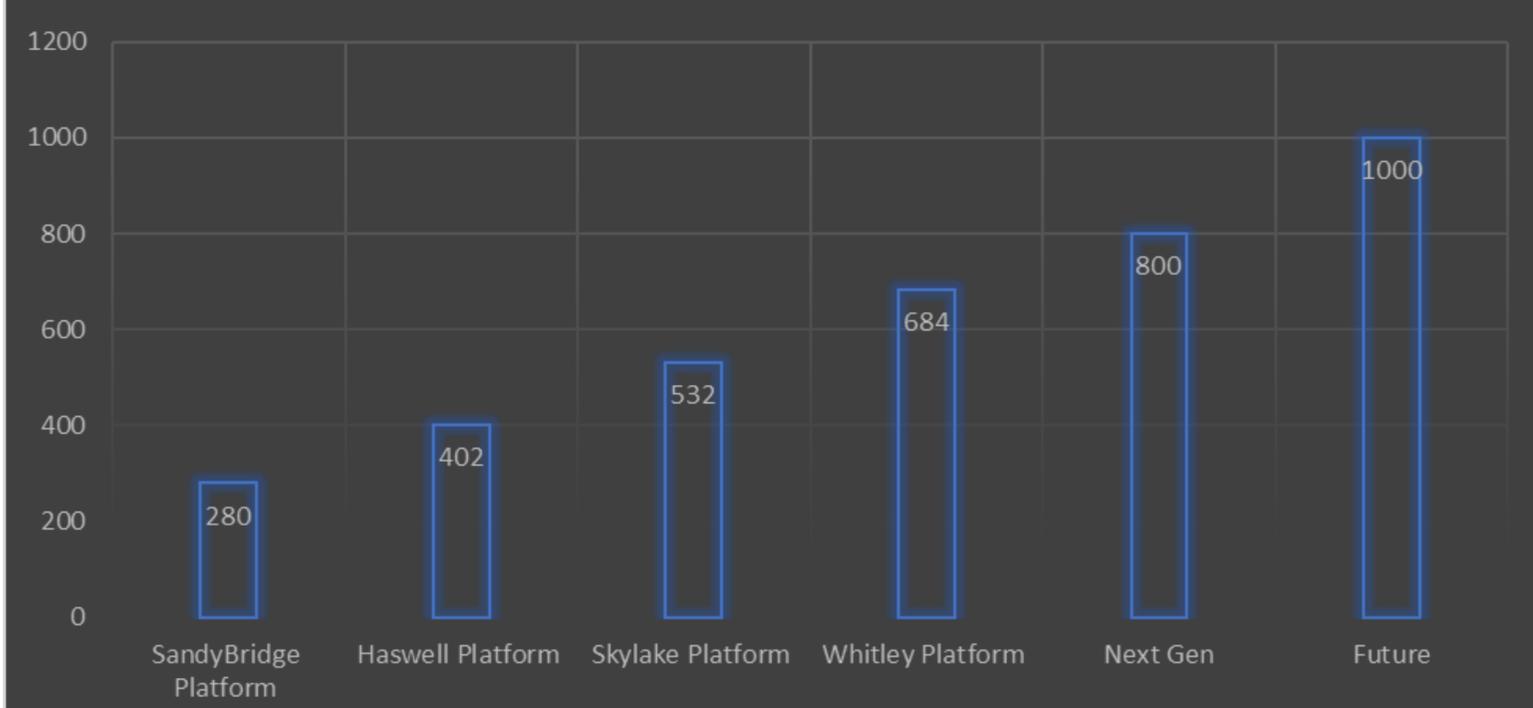
Source: EMC "Digital Universe Study" with data and analysis by IDC // April 2014

Background : Computing drives devices into higher power consumption

GPU Vs CPU TDP Trend



1U server power(100% loading)



➤ Computing drives devices into higher power consumption.

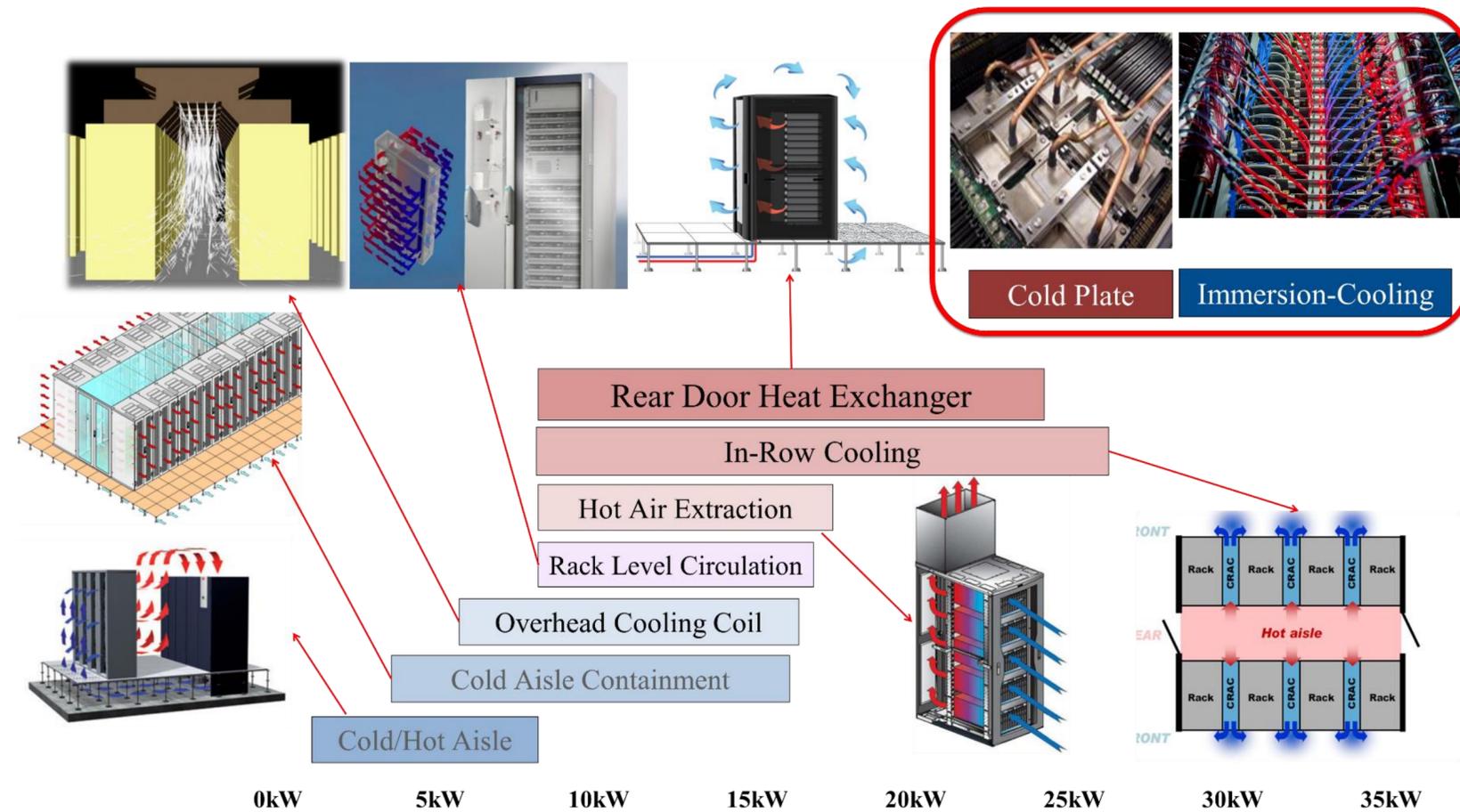
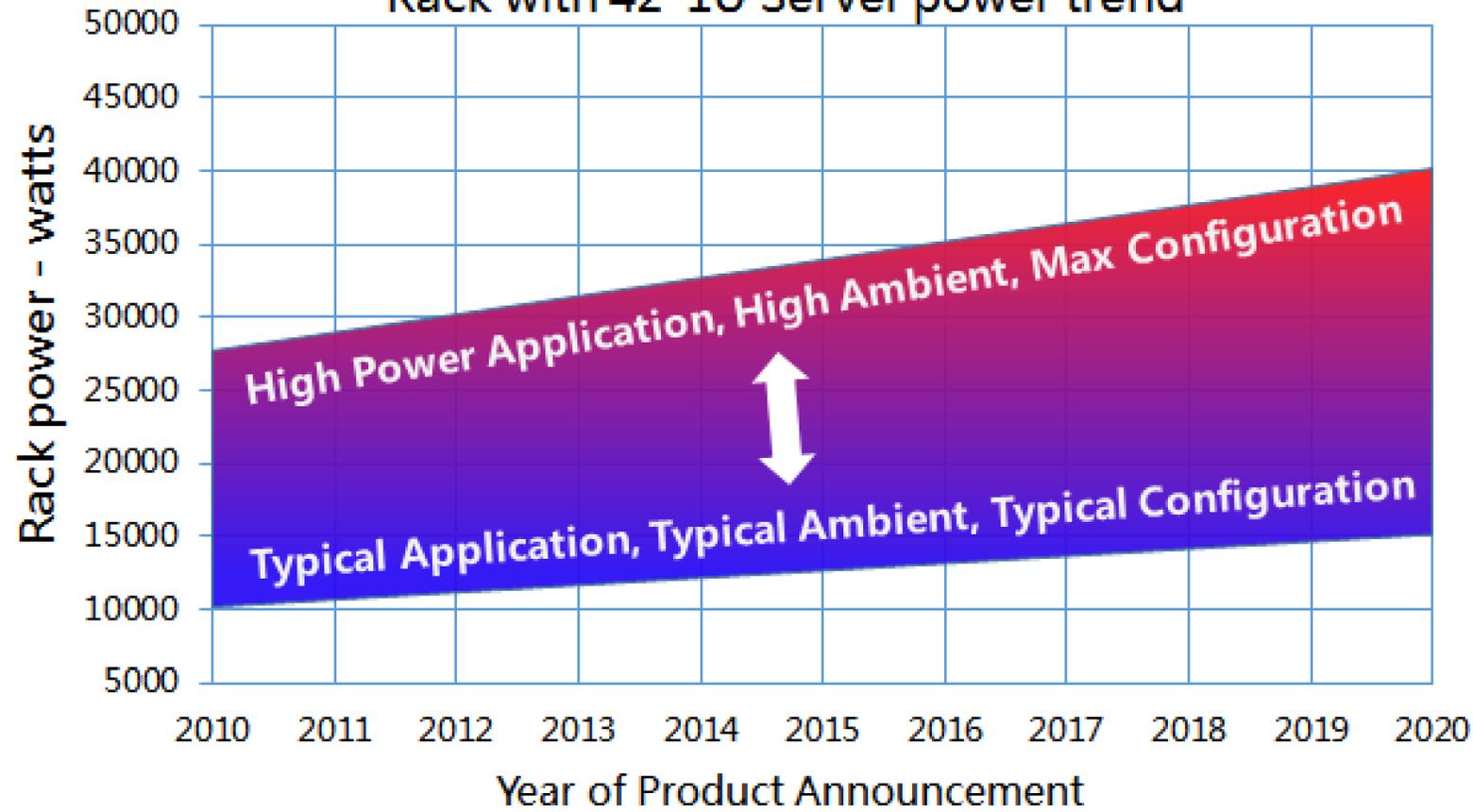
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Today's Datacenter Challenges

1. high power density racks' cooling

Rack with 42*1U Server power trend



Datacom Equipment Power Trends and Cooling Applications --ASHRAE

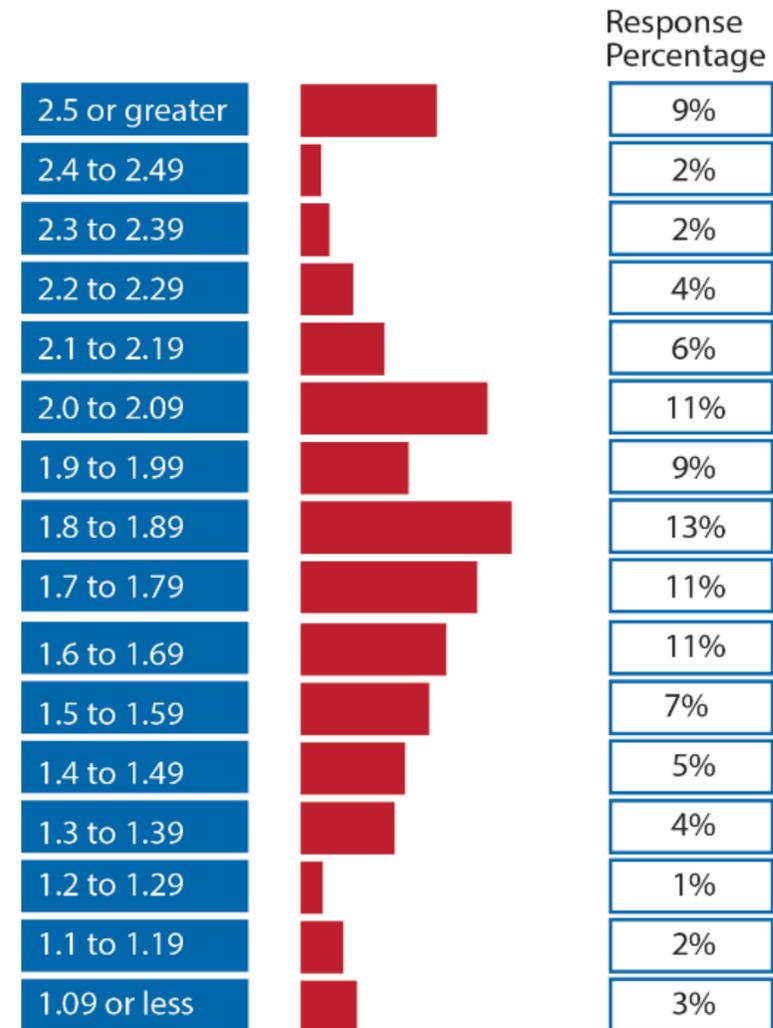
- Computing drives devices into higher power consumption. Rack power density is growing rapidly
- Air-Cooling cannot meet the heat dissipation demand any more

Today's Datacenter Challenges

2. PUE/TCO

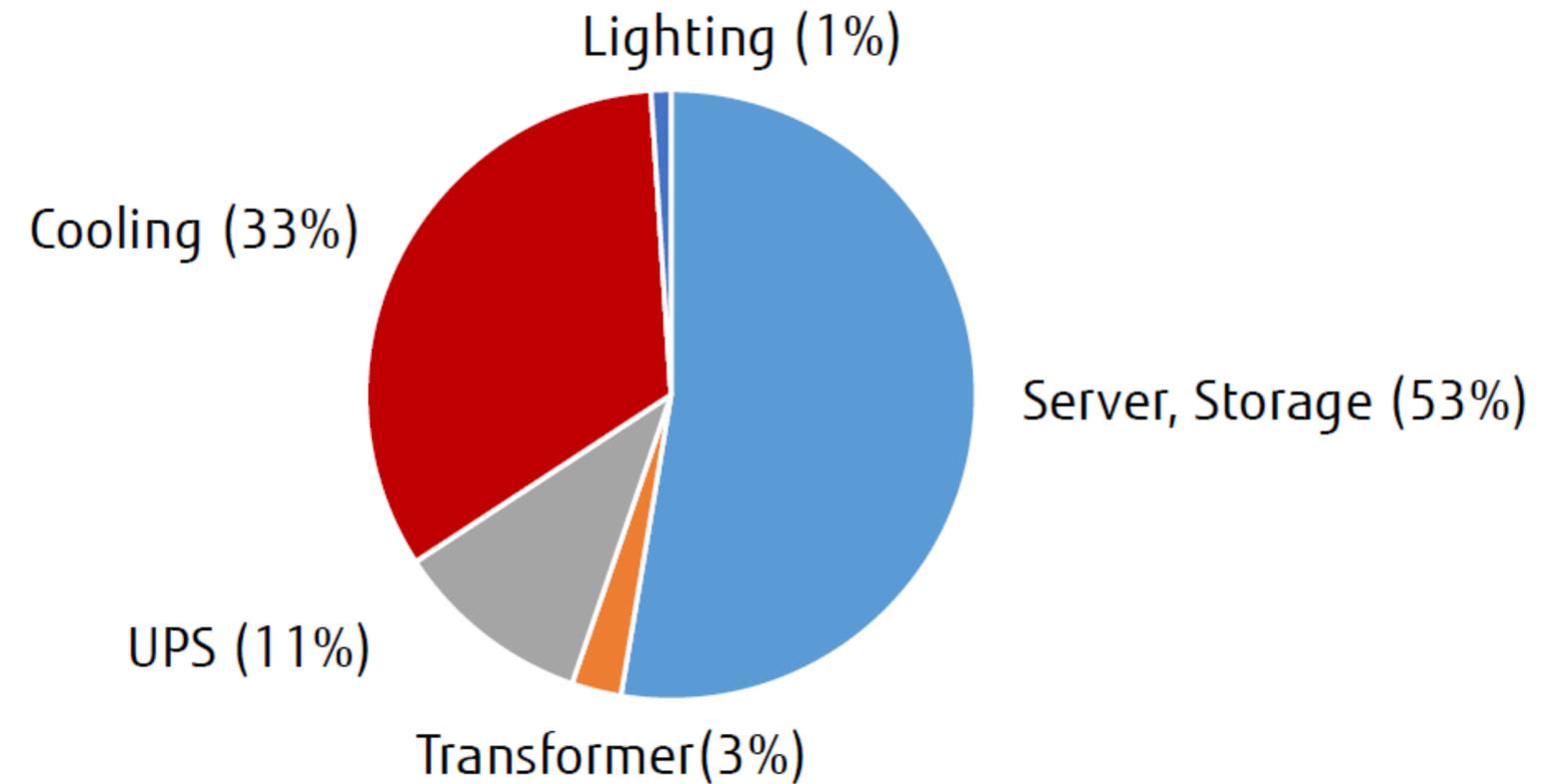
$$\text{Data center Power usage effectiveness(PUE)} = \frac{\text{Total data center power (kw)}}{\text{Total IT Power (kw)}}$$

Average PUE of your largest data center:



AVERAGE PUE 1.8 – 1.89

Source : Uptime Institute survey of over 1100 data centers



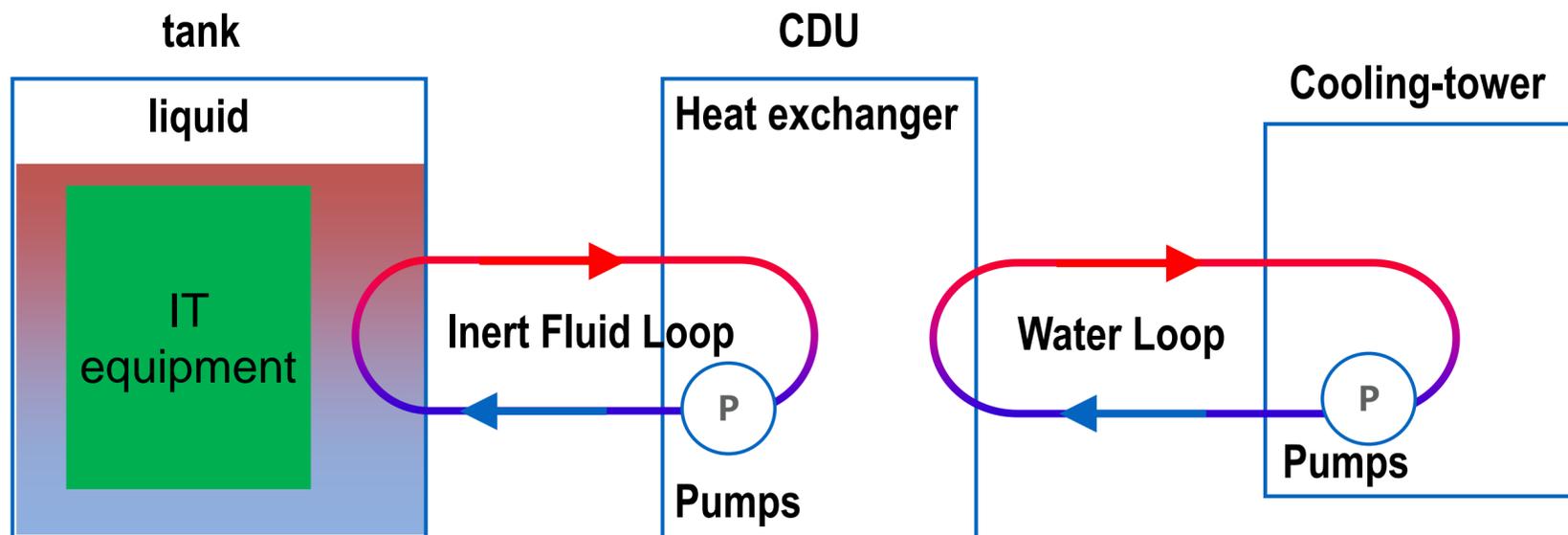
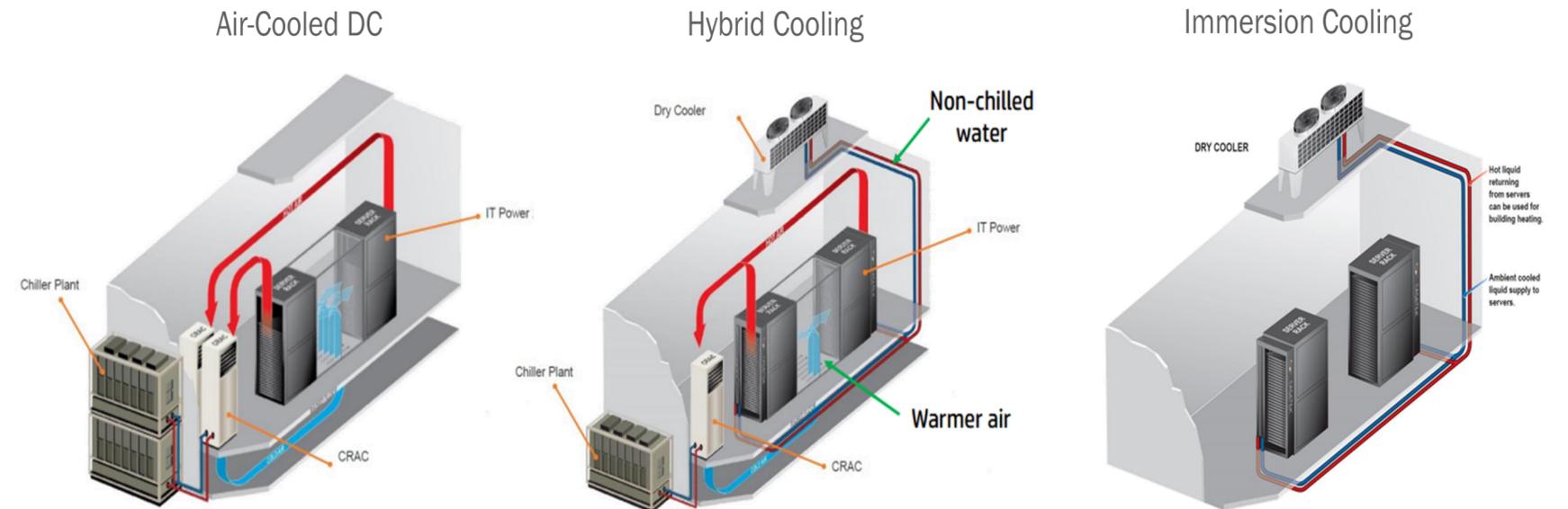
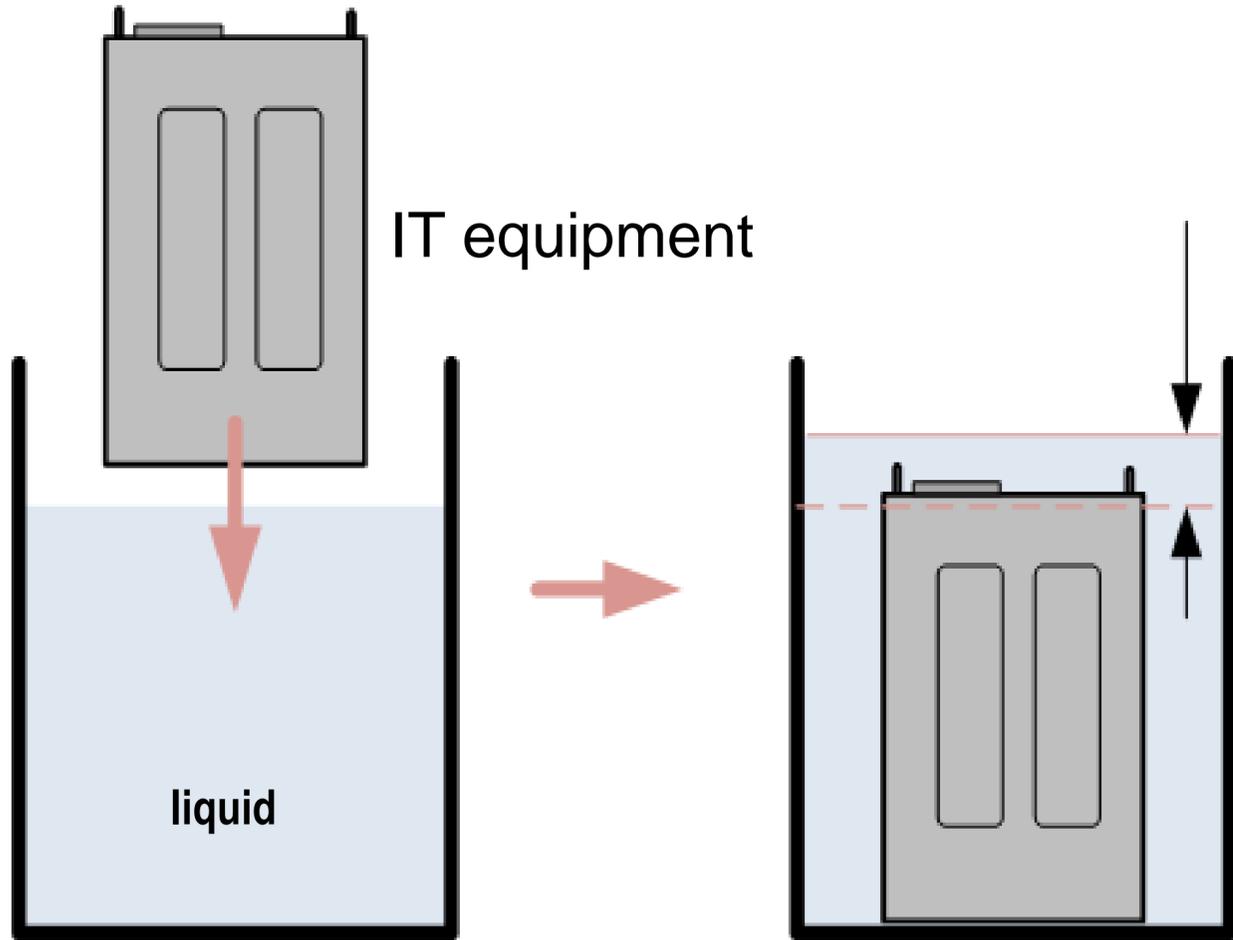
*A Shehabi: LAWRENCE BERKELEY NATIONAL LABORATORY "United States Data Center Energy Usage Report", 2016.

- The energy consumption of the data center for cooling is quite large.
- How to achieve low PUE and optimized TCO? That has become a new challenge.

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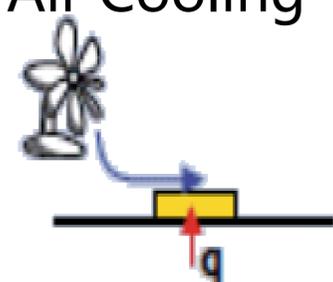
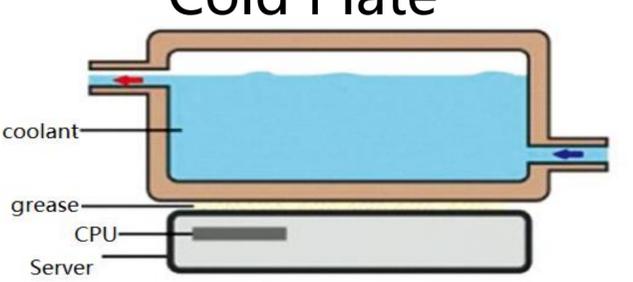
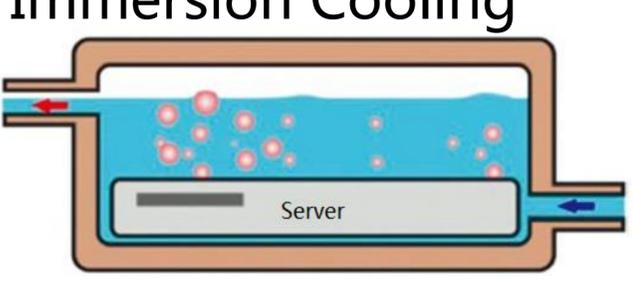
What is immersion cooling?



➤ **Liquid (3M Fluids) has better Specific Heat Capacity than air.**

➤ **No CRAC in IDC, low PUE 1.05-1.07**

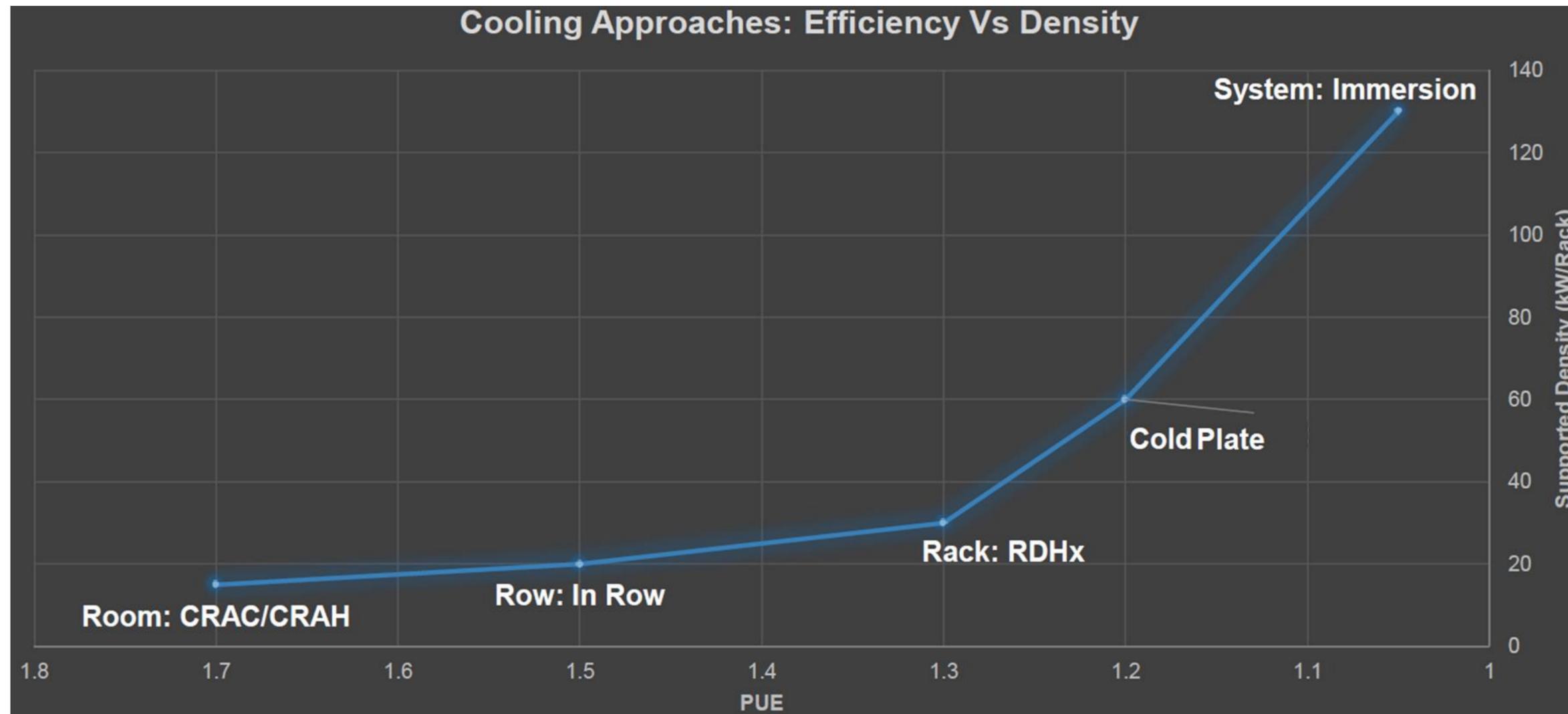
Why immersion cooling?

	Air Cooling	Cold Plate	Immersion Cooling	
				0 means “Base Line” + means “Better” - means “Worse”
Cooling Capacity	0	+	++	Immersion Cooling is the best.
Hardware Integration	0	+	++	No fans in immersion Cooling.
Maintenance	0	--	-	New mechanical design.
Hardware Reliability	0	-	+	Unaffected by dust , humidity and vibration.
Hardware Performance	0	+	++	Cooling helps improving performance.
Energy Efficiency	0	+	++	No fans, chillers, CRAHs.
Heat Recovery	0	+	++	Easy to be recovered from liquid.
Noise	0	+	++	No fans, no noise.
Corrosion	0	+	++	Isolation from air, no corrosion.
Material Compatibility	0	0	?	Material compatibility needs to be tested.
Initial Capex	0	-	--	Liquid cost is temporarily high.
Opex	0	+	++	No fans, chillers, CRAHs. Low PUE.
Weight	0	-	--	Liquid is heavy.

Advantages of immersion cooling: (1) Best cooling capacity (2) lowest TCO/PUE

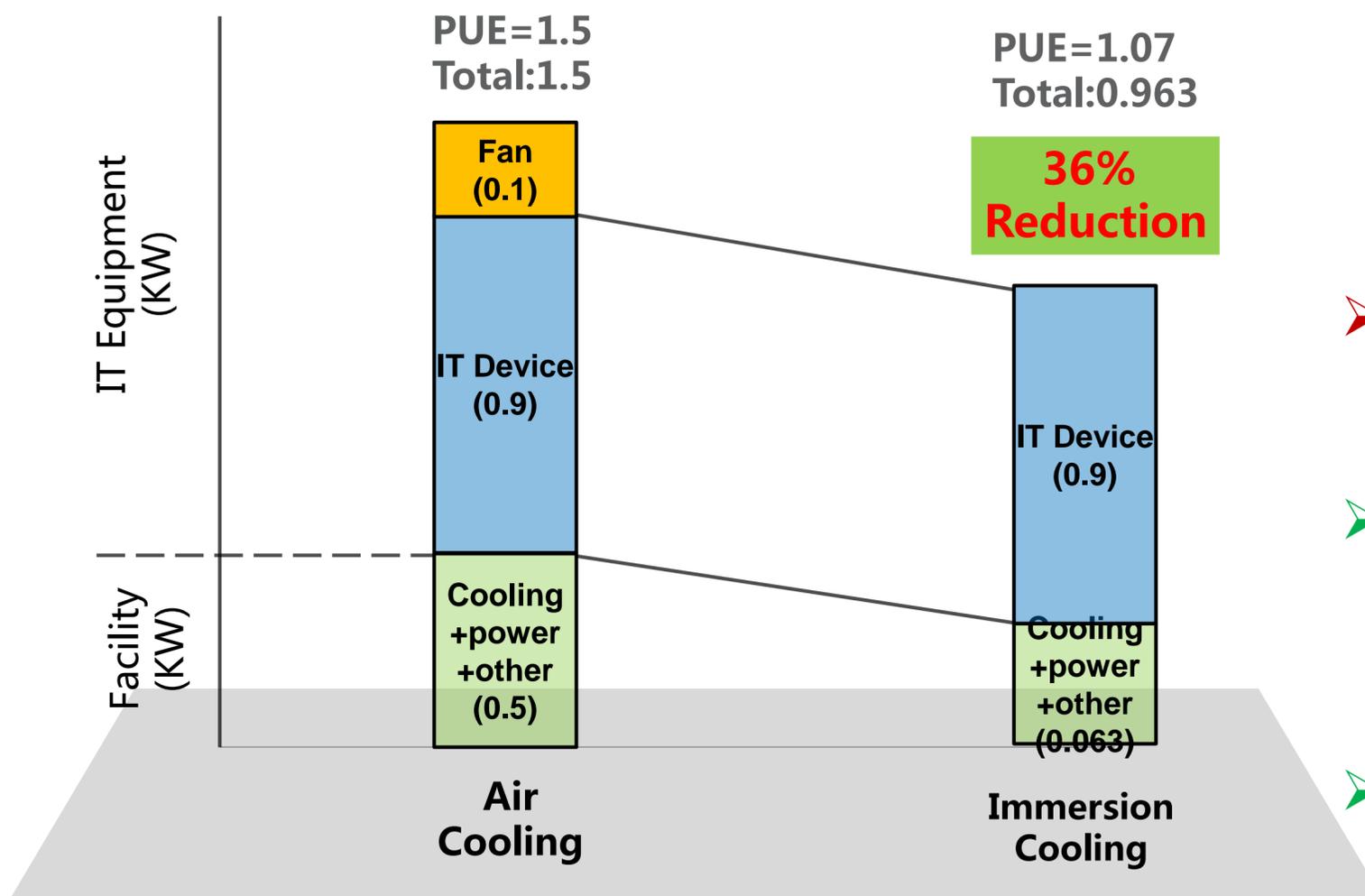
Why immersion-cooling?

300%+ Higher Density



Why immersion cooling?

Power consumption comparison
Air-cooling Vs immersion cooling

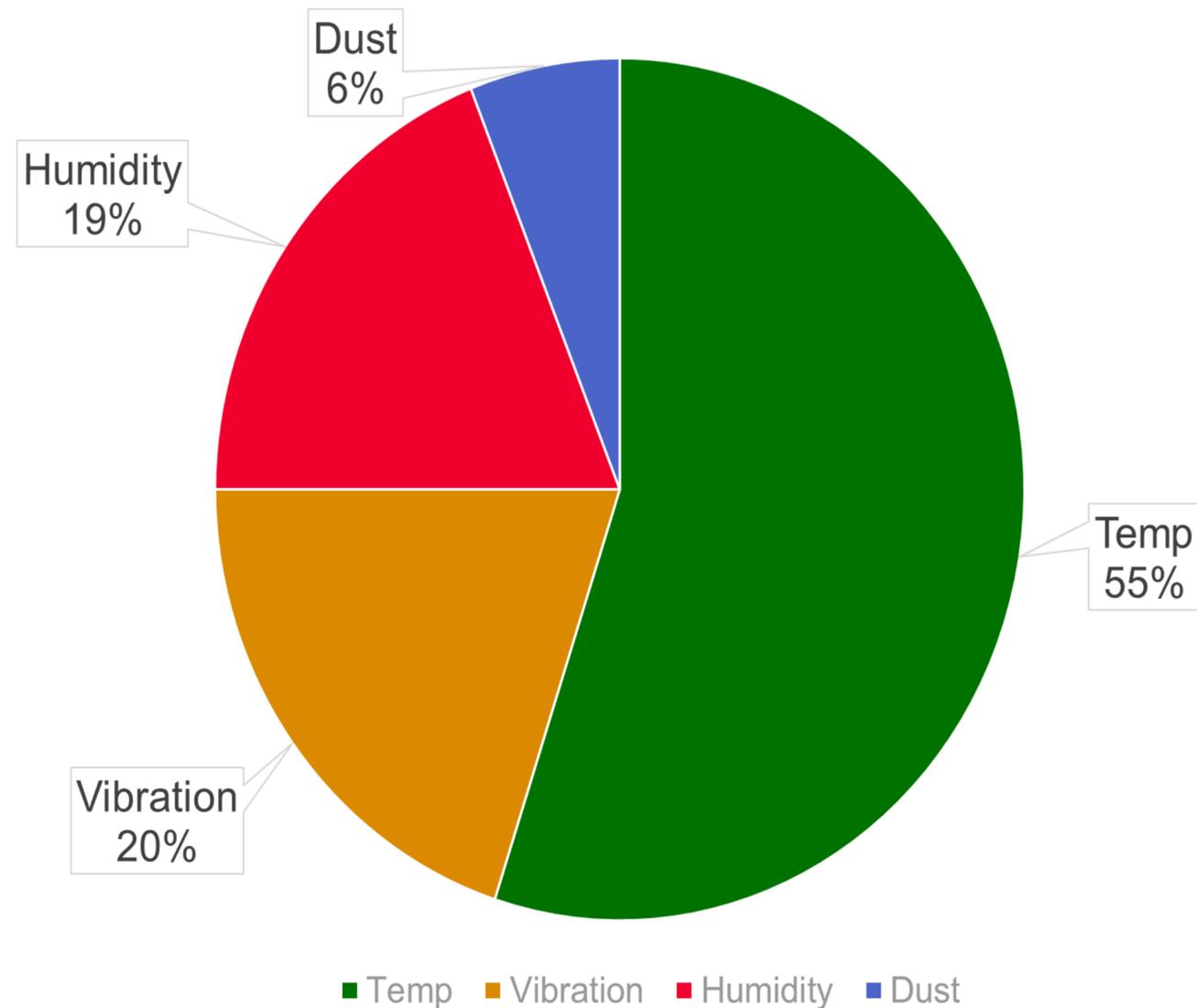


Less Power Consumption
Less Carbon emission
Better TCO

- **36% less power by using immersion cooling**
- **Reduce 3 tons carbon dioxide emission per IT KW per year**
- **TCO optimization**

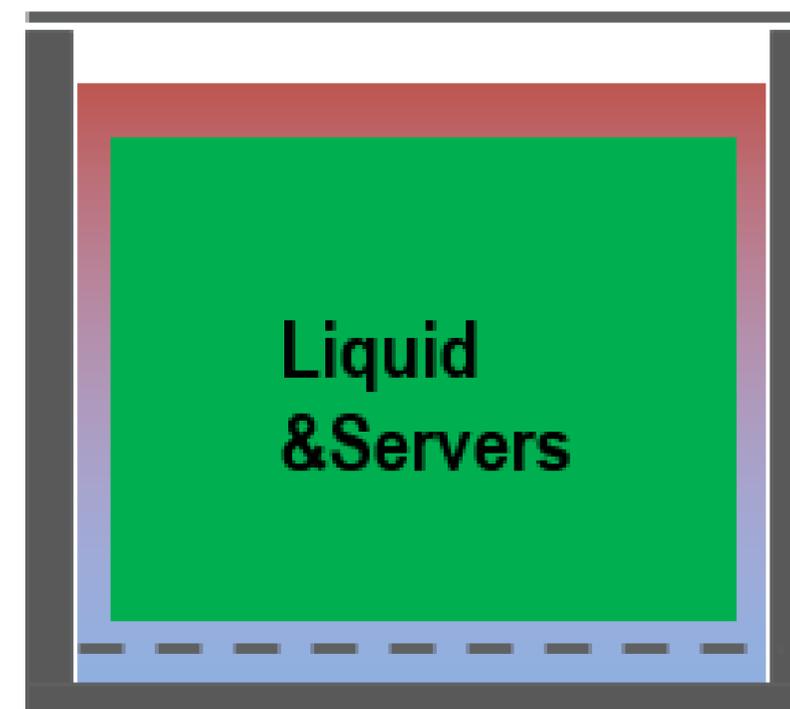
Why immersion cooling?

Major Causes of Electronic Failures



Source: US Air Force Avionics Integrity Program

Higher Reliability



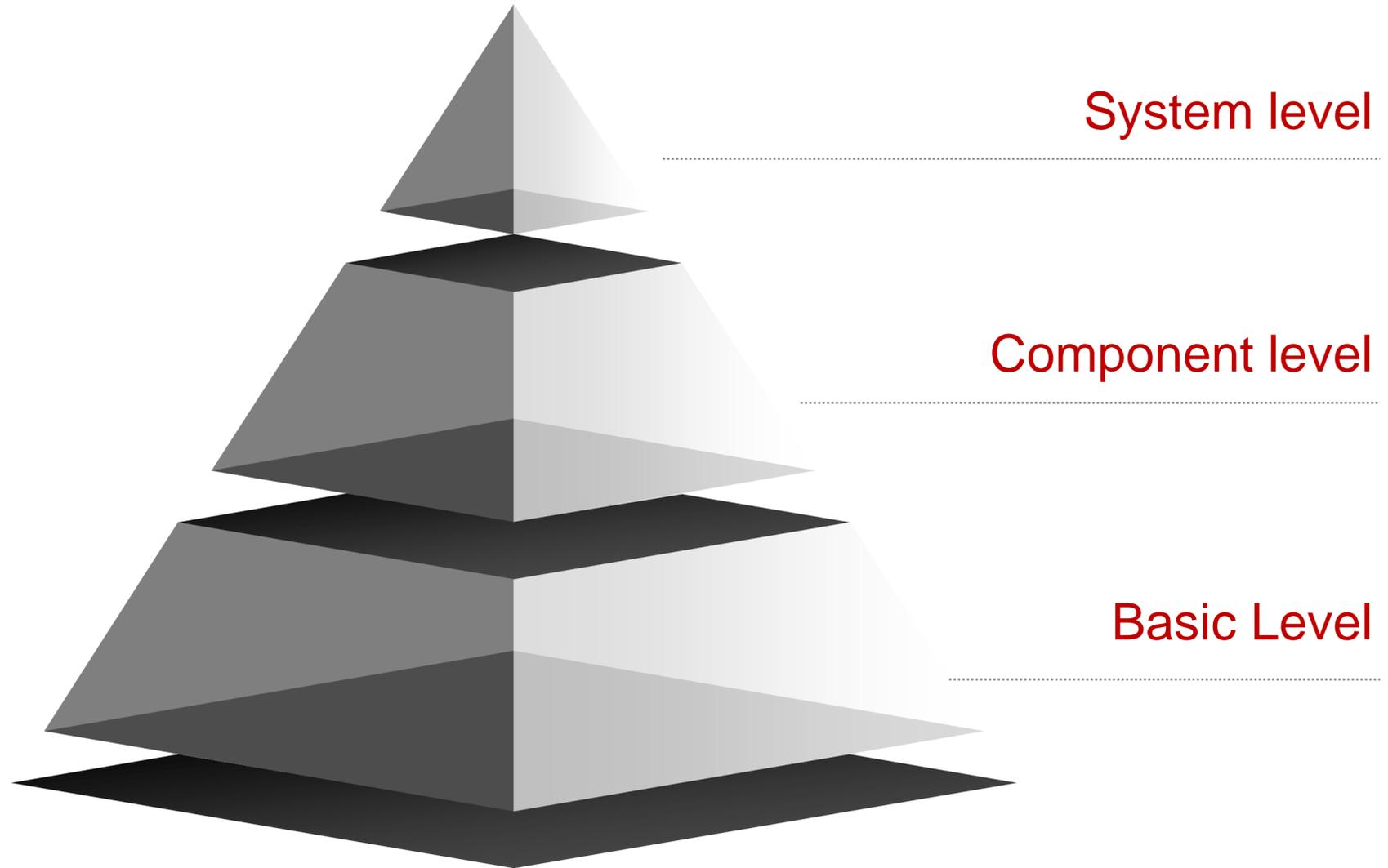
Tank

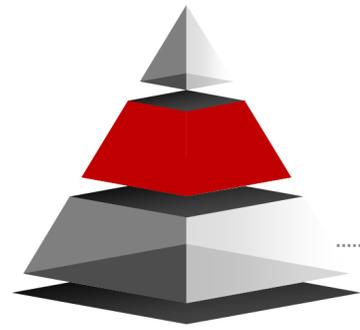
Liquid protects IT devices from harsh environment including high temperature, humidity, vibration, dust

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The challenge of immersion cooling





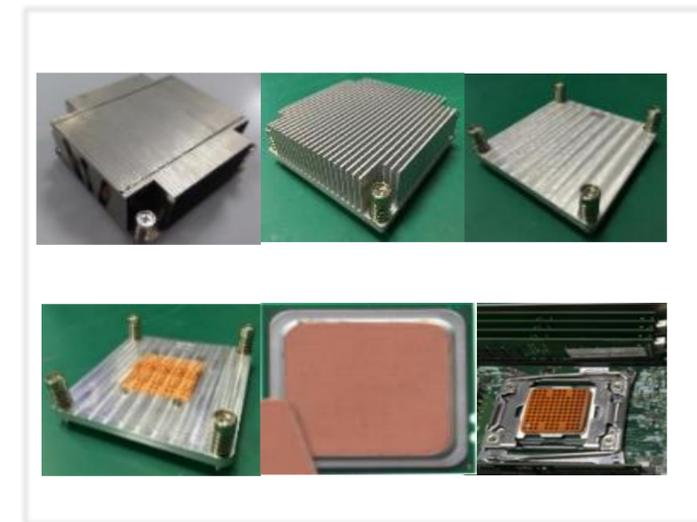
Basic Level



Material Compatibility



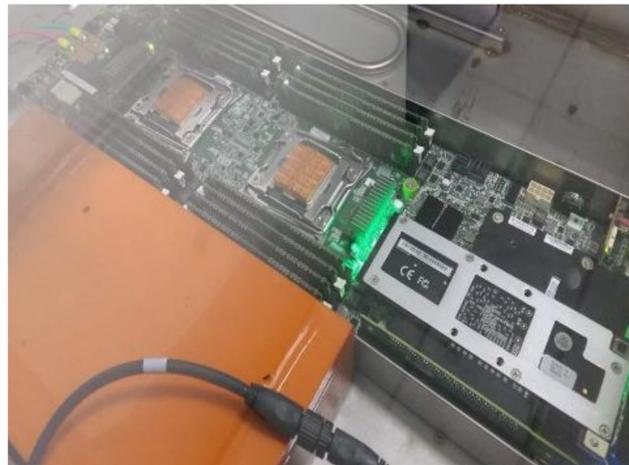
Signal Integrity
(PCB/ CONN)



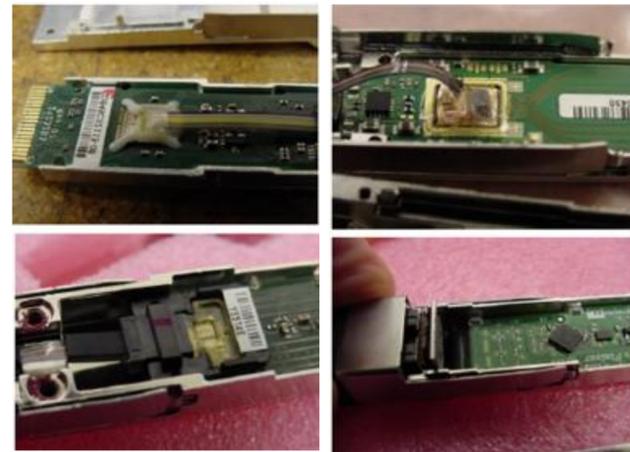
Heat Dissipation
Surface Treatment



Component Level



CPU, Storage, Memory,
HBA

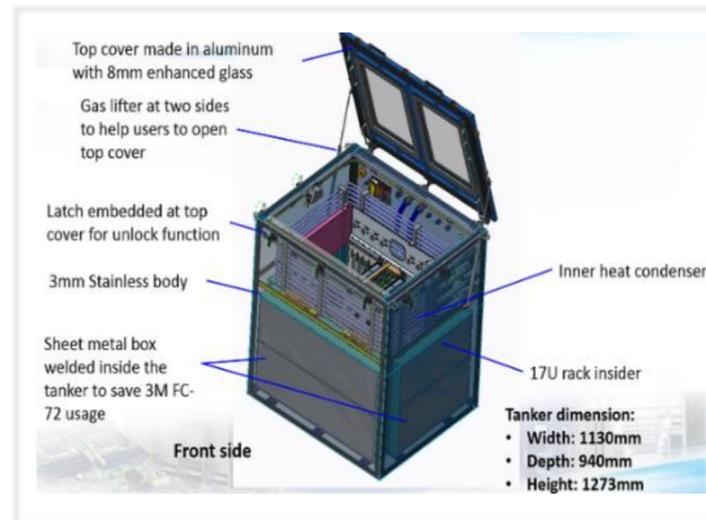
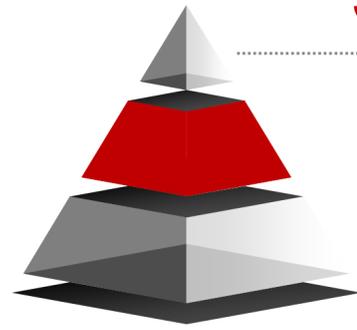


Optical Devices

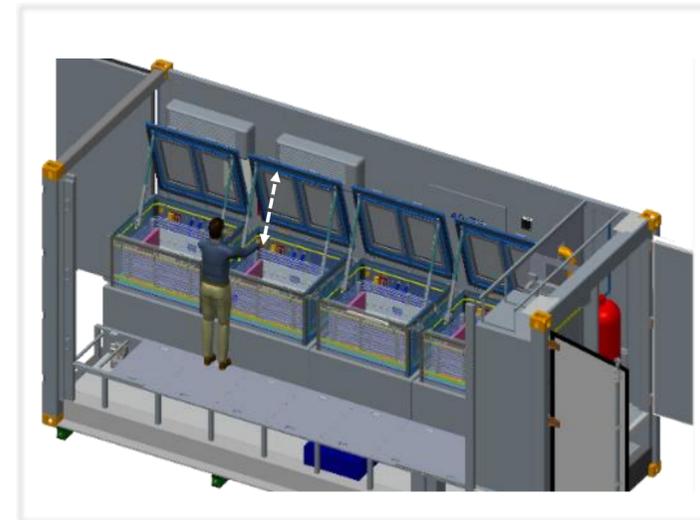


Performance, Stability,
Energy efficiency

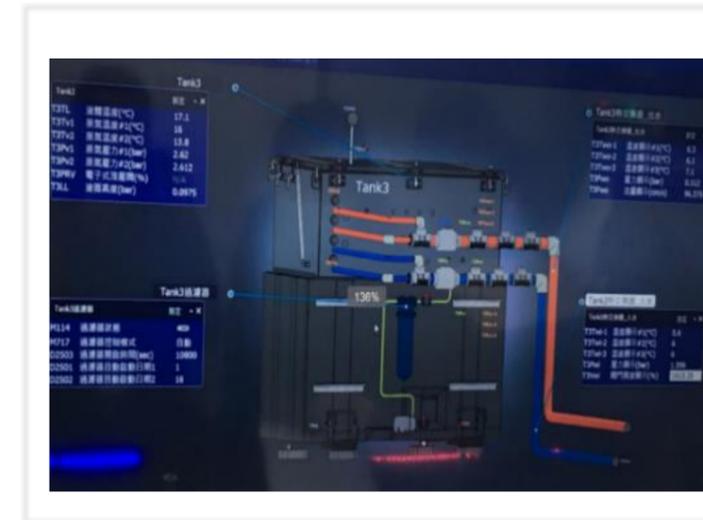
System Level



Server architecture,
Tank sealing,
Maintainability,
Space utilization



Data center architecture
CDU pipe layout



Monitoring and
Management system

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Alibaba Progress and Plan

2017

2018

2019

2020



Phase 1

Design & Validation&Pilot Run

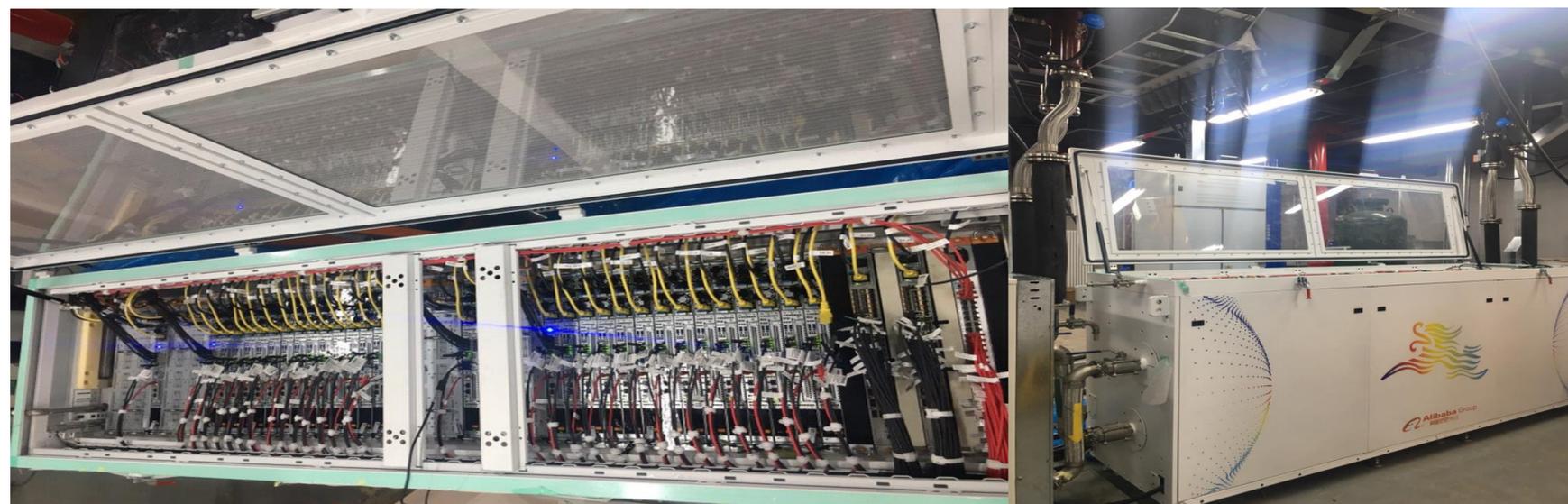
Server/Tank/IDC/Network product long term reliability data collection

Maintain operation consolidation



Phase 2

High power density co-design and mass deployment



1. Immersion cooling is a better way to tackle the high power density challenges
2. Immersion cooling is not far away , but still needs ecosystem partners to support
3. Alibaba is the first CSP to deploy the immersion cooling systems, willing to contribute to the community



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